

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended) A semiconductor device production apparatus comprising:

- a rotary table section including a rotary table for supporting a wafer thereon;
- a chamber for housing the rotary table section;
- a heater provided in the chamber for heating the wafer;
- a temperature sensing ~~device~~ element for sensing a temperature of the wafer;
- a temperature measuring section for converting the sensed temperature into a first signal to output the first signal; and
- a signal generating section for converting the output first signal into a second signal detectable from outside the chamber;

wherein the temperature sensing ~~device~~ element, the temperature measuring section and the signal generating section are attached to the rotary table section, and a distal end of the temperature sensing element projects outwardly from a surface of the rotary table so as to be brought into close relation to or in contact with a bottom surface of the wafer.

2. (Currently amended) A semiconductor device production apparatus as set forth in claim 1, wherein the temperature sensing ~~device~~ element comprises ~~includes~~ a thermocouple.

3. (Original) A semiconductor device production apparatus as set forth in claim 1, wherein the signal generating section comprises a detachable storage device for converting the first signal into a storage data to store the storage data as the second signal.

4. (Original) A semiconductor device production apparatus as set forth in claim 1, wherein the signal generating section comprises a wireless transmitter for converting the first signal into a wireless signal to transmit the wireless signal as the second signal.

5. (Original) A semiconductor device production apparatus as set forth in claim 1, wherein the signal generating section comprises a display device for converting the first signal into display data to display the display data as the second signal.

6. (Original) A semiconductor device production apparatus as set forth in claim 3, further comprising a storage data reader for read out the storage data from the storage device and a heater controlling section for controlling the heater on the basis of the read out storage data, the storage data reader and the heater controlling section being provided outside the chamber.

7. (Original) A semiconductor device production apparatus as set forth in claim 4, further comprising a receiver for receiving the wireless signal from the transmitter, and a heater controlling section for controlling the heater on the basis of the received signal, the receiver and the heater controlling section being provided outside the chamber.

8. (Withdrawn) A semiconductor device production method comprising the steps of:
providing a semiconductor device production apparatus as recited in claim 1;
placing a wafer on the rotary table;
heating the wafer by the heater;

supplying a material gas into the chamber;
detecting the second signal outside the chamber; and
controlling the heater on the basis of the detected second signal for production of
a semiconductor device.

9. (New) The semiconductor device production apparatus of claim 1, further comprising
a cooling section for cooling at least one of the temperature measuring section and the signal
generating section.

10. (New) The semiconductor device production apparatus of claim 9, wherein the
cooling section includes a circulating system of cooling water.

11. (New) A semiconductor device production apparatus comprising:
a rotary table section including a rotary table for supporting a wafer;
a chamber for housing the rotary table section;
a heater provided in the chamber for heating the wafer;
a temperature sensing device for sensing a temperature of the wafer;
a temperature measuring section for converting the sensed temperature into a first signal
to output the first signal;
a signal generating section for converting the output first signal into a second signal
detectable from outside the chamber; and
a cooling section for cooling at least one of the temperature measuring section and the
signal generating section;

wherein the temperature sensing device, the temperature measuring section and the signal generating section are attached to the rotary table section.

12. (New) The semiconductor device production apparatus of claim 11, wherein the cooling section includes a circulating system of cooling water.